

DATASHEET

High Power Infrared LED EAIST3045A1



Features

- Small package with high efficiency
- Peak wavelength $\lambda p = 850$ nm
- Soldering methods :SMT
- Thermal resistance (junction to lead): $18^{\circ}C/W$.
- Pb free
- The product itself will remain within RoHS compliant version.

Description

- EAIST3045A1 series is an infrared emitting diode in miniature SMD package which is molded in a water clear silicone with spherical top view lens.
- The device is spectrally matched with silicon photodiode, Phototransistor.

Applications

- CCD Camera
- Infrared applied system

Device Selection Guide

Chip Materials	Emitted Color	Resin Color
AlGaAs	Infrared	Water Clear

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Continuous Forward Current	I _F	500	mA
Peak Forward Current *1	IFP	1.0	А
Reverse Voltage	VR	5	V
Operating Temperature	Topr	-40~ +85	°C
Storage Temperature	Tstg	-40 ~ +100	°C
Junction temperature	Tj	115	°C
Thermal resistance (junction to leadframe)	Rth(j-L)	18	°C <i>I</i> W
Power Dissipation @IF=500mA	Pd	1	W

Notes:

*1:I_{FP} Conditions--Pulse Width ${\leq}\,100\mu s$ and Duty ${\leq}\,1\%.$

*2Note: We suggest that customer should add the heat sink with EAIST3045A1 to exclude the heat.

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Total Radiated Power	Po	150	210		mW	I _F =350mA
		200	270			I _F =500mA
		400	500			I _F =1000mA
Radiant Intensity	Ι _Ε		65		mWsr	I _F =500mA
Peak Wavelength	λр		850		nm	I _F =500mA
Spectral Bandwidth	Δλ		40		nm	I _F =500mA
Forward Voltage	V	1.4	2.0		V	I _F =350mA
	V _F	1.6	2.2			I _F =500mA
Reverse Current	I _R			10	μA	V _R =5V
View Angle	201/2		130		deg	I _F =20mA

Bin Code List

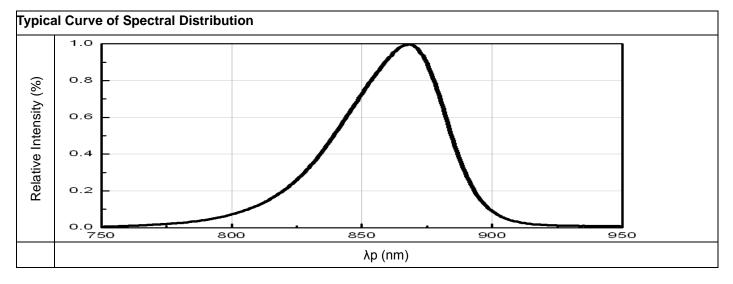
Condition : I_F=350mA Radiated Power

Unit : mW

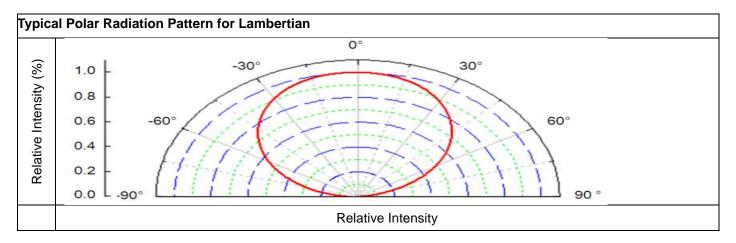
Bin Number	Α	В	С	D	E
Min	120	170	218	264	305
Max	190	242	295	345	385

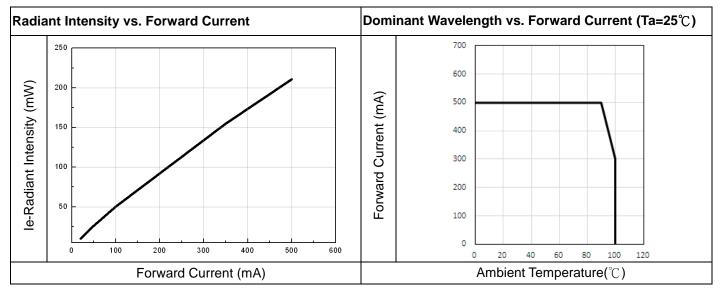
Including test tolerance ±10%

Typical Electro-Optical Characteristics Curves



Note: V(λ)=Standard eye response curve; I_F =20mA

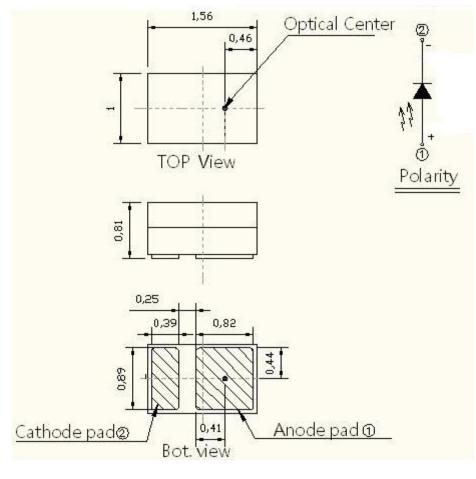




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Package Dimension



Note:

- 1. Dimensions are in millimeters.
- 2. Tolerances unless mentioned are ± 0.1 mm.

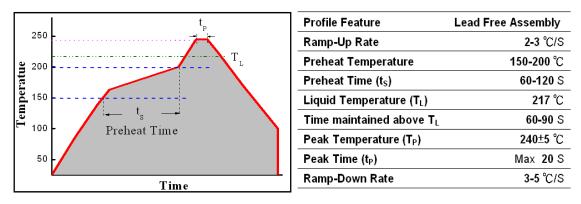
Pad Configuration

Bot. view	TOP View	
PAD	FUNCTION	
1	ANODE	
2	CATHODE	
Р	THERMAL PAD	

Reflow Soldering Characteristics

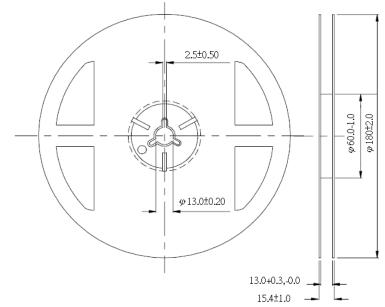
For Reflow Process

- a. C16 series are suitable for SMT processes.
- b. Curing of glue in oven must be according to standard operation flow processes.



- c. Reflow soldering should not be done more than twice.
- d. In soldering process, stress on the LEDs during heating should be avoided.
- e. After soldering, do not bend the circuit board.

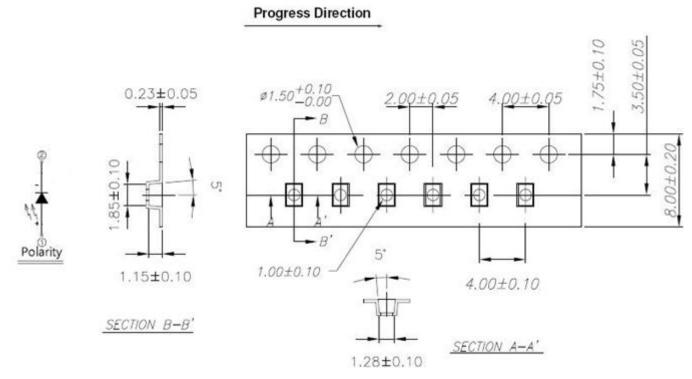
Package Dimensions



Note: 1. Dimensions are in millimeters

2. The tolerances unless mentioned is ±0.1mm

Carrier Tape Dimensions: Loaded quantity 2000 PCS per reel.

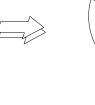


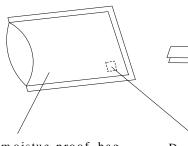
Note: 1. Dimensions are in millimeters

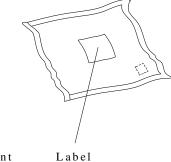
2. The tolerances unless mentioned is ±0.1mm

Moisture Resistant Packaging









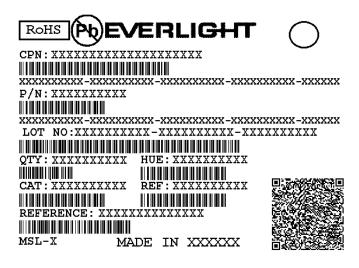
Label

Aluminum moistue-proof bag

Desiccant

Moisture Resistant Packing Materials

Label Form Specification



CPN: Customer's Production Number P/N : Production Number QTY: Packing Quantity CAT: Ranks HUE: Peak Wavelength REF: Reference LOT No: Lot Number MADE IN TAIWAN: Production Place

Notes

- 1. Above specification may be changed without notice. EVERLIGHT will reserve authority on material change for above specification.
- When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute
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